

PZUxB series

Single Zener diodes in a SOD323F package

Rev. 02 — 15 November 2009

Product data sheet

1. Product profile

1.1 General description

General-purpose Zener diodes in a SOD323F (SC-90) very small and flat lead Surface Mounted Device (SMD) plastic package.

1.2 Features

- Total power dissipation: ≤ 310 mW
- Tolerance series: B: approximately ± 5 %; B1, B2, B3: sequential, approximately ± 2 %
- Small plastic package suitable for surface mounted design
- Wide working voltage range: nominal 2.4 V to 36 V

1.3 Applications

- General regulation functions

1.4 Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------|-------------------------|----------------------|-------|-----|-----|------|
| V_F | forward voltage | $I_F = 100$ mA | [1] - | - | 1.1 | V |
| P_{tot} | total power dissipation | $T_{amb} \leq 25$ °C | [2] - | - | 310 | mW |
| | | | [3] - | - | 550 | mW |


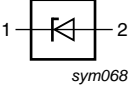
[1] Pulse test: $t_p \leq 300$ μ s; $\delta \leq 0.02$

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1cm².

2. Pinning information

Table 2. Pinning

| Pin | Description | Simplified outline | Symbol |
|-----|-------------|---|---|
| 1 | cathode |  |  sym068 |
| 2 | anode | | |

[1] The marking bar indicates the cathode

3. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|----------------------|---------|--|---------|
| | Name | Description | Version |
| PZU2.4B to PZU36B[1] | SC-90 | plastic surface mounted package; 2 leads | SOD323F |

[1] The series consists of 97 types with nominal working voltages from 2.4 V to 36 V.

4. Marking

Table 4. Marking codes

| Type number | Marking code | | | | Type number | Marking code | | | |
|-------------|--------------|----|----|----|-------------|--------------|----|----|----|
| | B | B1 | B2 | B3 | | B | B1 | B2 | B3 |
| PZU2.4 | G3 | - | - | - | PZU10 | GJ | FH | HF | KB |
| PZU2.7 | G4 | F3 | H1 | - | PZU11 | GK | FJ | HG | KC |
| PZU3.0 | G5 | F4 | H2 | - | PZU12 | GL | FK | HH | KD |
| PZU3.3 | G6 | F5 | H3 | - | PZU13 | GM | FL | HJ | KE |
| PZU3.6 | G7 | F6 | H4 | - | PZU14 | - | - | HK | - |
| PZU3.9 | G8 | F7 | H5 | - | PZU15 | GN | FM | HL | KF |
| PZU4.3 | G9 | F8 | H6 | HS | PZU16 | GP | FN | HM | KG |
| PZU4.7 | GA | F9 | H7 | HT | PZU18 | GQ | FP | HN | KH |
| PZU5.1 | GB | FA | H8 | HU | PZU20 | GR | FQ | HP | KJ |
| PZU5.6 | GC | FB | H9 | HV | PZU22 | GS | FR | HQ | KK |
| PZU6.2 | GD | FC | HA | HW | PZU24 | GT | FS | HR | KL |
| PZU6.8 | GE | FD | HB | HX | PZU27 | GU | - | - | - |
| PZU7.5 | GF | FE | HC | HY | PZU30 | GV | - | - | - |
| PZU8.2 | GG | FF | HD | HZ | PZU33 | GW | - | - | - |
| PZU9.1 | GH | FG | HE | KA | PZU36 | GX | - | - | - |

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|---|-----------------------------|-------|---|------|
| I_F | forward current | | - | 200 | mA |
| I_{ZSM} | non-repetitive peak reverse current | | - | see Table 8 and 9 | |
| P_{ZSM} | non-repetitive peak reverse power dissipation | | [1] - | 40 | W |
| P_{tot} | total power dissipation | $T_{amb} \leq 25\text{ °C}$ | [2] - | 310 | mW |
| | | | [3] - | 550 | mW |
| T_j | junction temperature | | - | 150 | °C |
| T_{amb} | ambient temperature | | -65 | +150 | °C |
| T_{stg} | storage temperature | | -65 | +150 | °C |

[1] $t_p = 100\ \mu\text{s}$; square wave; $T_j = 25\text{ °C}$ prior to surge

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

6. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|--|-------------|-------|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] - | - | 400 | K/W |
| | | | [2] - | - | 230 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | [3] - | - | 55 | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

[3] Soldering point of cathode tab

7. Characteristics

Table 7. Characteristics

$T_j = 25\text{ °C}$ unless otherwise specified

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------|-----------------|-----------------------|-------|-----|-----|------|
| V_F | forward voltage | $I_F = 10\text{ mA}$ | [1] - | - | 0.9 | V |
| | | $I_F = 100\text{ mA}$ | [1] - | - | 1.1 | V |

[1] Pulse test: $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$

Table 8. Characteristics per type; PZU2.4B to PZU5.6B3

 $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

| PZU xxx | Sel | Working voltage V_Z (V); $I_Z = 5\text{ mA}$ | | Maximum differential resistance r_{dif} (Ω) | | Reverse current I_R (μA) | | Temperature coefficient S_Z (mV/K); $I_Z = 5\text{ mA}$ | Diode capacitance C_d (pF) ^[1] | Non-repetitive peak reverse current I_{ZSM} (A) ^[2] |
|------------|-----|---|------|---|---------------------|---|-----------|--|---|--|
| | | Min | Max | $I_Z = 0.5\text{ mA}$ | $I_Z = 5\text{ mA}$ | Max | V_R (V) | Typ | Max | Max |
| 2.4 | B | 2.3 | 2.6 | 1000 | 100 | 50 | 1 | -1.6 | 450 | 8 |
| 2.7 | B | 2.5 | 2.9 | 1000 | 100 | 20 | 1 | -2.0 | 440 | 8 |
| | B1 | 2.5 | 2.75 | | | | | | | |
| | B2 | 2.65 | 2.9 | | | | | | | |
| 3.0 | B | 2.80 | 3.20 | 1000 | 95 | 10 | 1 | -2.1 | 425 | 8 |
| | B1 | 2.80 | 3.05 | | | | | | | |
| | B2 | 2.95 | 3.20 | | | | | | | |
| 3.3 | B | 3.10 | 3.50 | 1000 | 95 | 5 | 1 | -2.4 | 410 | 8 |
| | B1 | 3.10 | 3.35 | | | | | | | |
| | B2 | 3.25 | 3.50 | | | | | | | |
| 3.6 | B | 3.40 | 3.80 | 1000 | 90 | 5 | 1 | -2.4 | 390 | 8 |
| | B1 | 3.40 | 3.65 | | | | | | | |
| | B2 | 3.55 | 3.80 | | | | | | | |
| 3.9 | B | 3.70 | 4.10 | 1000 | 90 | 3 | 1 | -2.5 | 370 | 8 |
| | B1 | 3.70 | 3.97 | | | | | | | |
| | B2 | 3.87 | 4.10 | | | | | | | |
| 4.3 | B | 4.01 | 4.48 | 1000 | 90 | 3 | 1 | -2.5 | 350 | 8 |
| | B1 | 4.01 | 4.21 | | | | | | | |
| | B2 | 4.15 | 4.34 | | | | | | | |
| | B3 | 4.28 | 4.48 | | | | | | | |
| 4.7 | B | 4.42 | 4.90 | 800 | 80 | 2 | 1 | -1.4 | 325 | 8 |
| | B1 | 4.42 | 4.61 | | | | | | | |
| | B2 | 4.55 | 4.75 | | | | | | | |
| | B3 | 4.69 | 4.90 | | | | | | | |
| 5.1 | B | 4.84 | 5.37 | 250 | 60 | 2 | 1.5 | 0.3 | 300 | 5.5 |
| | B1 | 4.84 | 5.04 | | | | | | | |
| | B2 | 4.98 | 5.20 | | | | | | | |
| | B3 | 5.14 | 5.37 | | | | | | | |
| 5.6 | B | 5.31 | 5.92 | 100 | 40 | 1 | 2.5 | 1.9 | 275 | 5.5 |
| | B1 | 5.31 | 5.55 | | | | | | | |
| | B2 | 5.49 | 5.73 | | | | | | | |
| | B3 | 5.67 | 5.92 | | | | | | | |

[1] $f = 1\text{ MHz}$; $V_R = 0\text{ V}$ [2] $t_p = 100\text{ }\mu\text{s}$; square wave; $T_j = 25\text{ }^\circ\text{C}$ prior to surge

Table 9. Characteristics per type; PZU6.2B to PZU36B

 $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

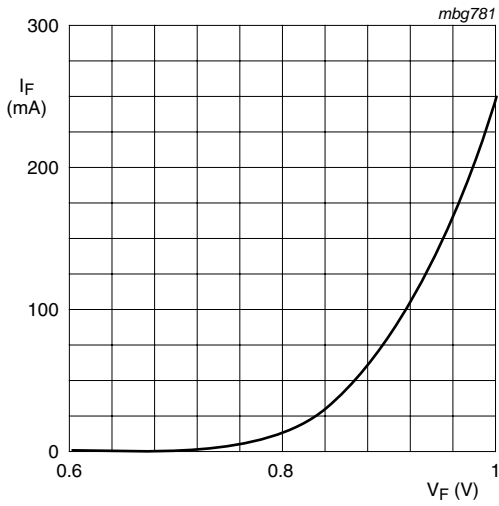
| PZU xxx | Sel | Working voltage V_Z (V); $I_Z = 5\text{ mA}$ | | Maximum differential resistance r_{dif} (Ω) | | Reverse current I_R (nA) | | Temperature coefficient S_Z (mV/K); $I_Z = 5\text{ mA}$ | Diode capacitance C_d (pF) ^[1] | Non-repetitive peak reverse current I_{ZSM} (A) ^[2] |
|------------|-----|---|-------|--|---------------------|----------------------------------|-----------|--|---|--|
| | | Min | Max | $I_Z = 0.5\text{ mA}$ | $I_Z = 5\text{ mA}$ | Max | V_R (V) | Typ | Max | Max |
| 6.2 | B | 5.86 | 6.53 | 80 | 30 | 500 | 3 | 2.7 | 250 | 5.5 |
| | B1 | 5.86 | 6.12 | | | | | | | |
| | B2 | 6.06 | 6.33 | | | | | | | |
| | B3 | 6.26 | 6.53 | | | | | | | |
| 6.8 | B | 6.47 | 7.14 | 60 | 20 | 500 | 3.5 | 3.4 | 215 | 5.5 |
| | B1 | 6.47 | 6.73 | | | | | | | |
| | B2 | 6.65 | 6.93 | | | | | | | |
| | B3 | 6.86 | 7.14 | | | | | | | |
| 7.5 | B | 7.06 | 7.84 | 60 | 10 | 500 | 4 | 4.0 | 170 | 3.5 |
| | B1 | 7.06 | 7.36 | | | | | | | |
| | B2 | 7.28 | 7.60 | | | | | | | |
| | B3 | 7.52 | 7.84 | | | | | | | |
| 8.2 | B | 7.76 | 8.64 | 60 | 10 | 500 | 5 | 4.6 | 150 | 3.5 |
| | B1 | 7.76 | 8.10 | | | | | | | |
| | B2 | 8.02 | 8.36 | | | | | | | |
| | B3 | 8.28 | 8.64 | | | | | | | |
| 9.1 | B | 8.56 | 9.55 | 60 | 10 | 500 | 6 | 5.5 | 120 | 3.5 |
| | B1 | 8.56 | 8.93 | | | | | | | |
| | B2 | 8.85 | 9.23 | | | | | | | |
| | B3 | 9.15 | 9.55 | | | | | | | |
| 10 | B | 9.45 | 10.55 | 60 | 10 | 100 | 7 | 6.4 | 110 | 3.5 |
| | B1 | 9.45 | 9.87 | | | | | | | |
| | B2 | 9.77 | 10.21 | | | | | | | |
| | B3 | 10.11 | 10.55 | | | | | | | |
| 11 | B | 10.44 | 11.56 | 60 | 10 | 100 | 8 | 7.4 | 108 | 3 |
| | B1 | 10.44 | 10.88 | | | | | | | |
| | B2 | 10.76 | 11.22 | | | | | | | |
| | B3 | 11.10 | 11.56 | | | | | | | |
| 12 | B | 11.42 | 12.60 | 80 | 10 | 100 | 9 | 8.4 | 105 | 3 |
| | B1 | 11.42 | 11.90 | | | | | | | |
| | B2 | 11.74 | 12.24 | | | | | | | |
| | B3 | 12.08 | 12.60 | | | | | | | |
| 13 | B | 12.47 | 13.96 | 80 | 10 | 100 | 10 | 9.4 | 103 | 2.5 |
| | B1 | 12.47 | 13.03 | | | | | | | |
| | B2 | 12.91 | 13.49 | | | | | | | |
| | B3 | 13.37 | 13.96 | | | | | | | |
| 14 | B2 | 13.70 | 14.30 | 80 | 10 | 100 | 11 | 10.4 | 101 | 2 |

Table 9. Characteristics per type; PZU6.2B to PZU36B ...continued

 $T_j = 25\text{ °C}$ unless otherwise specified

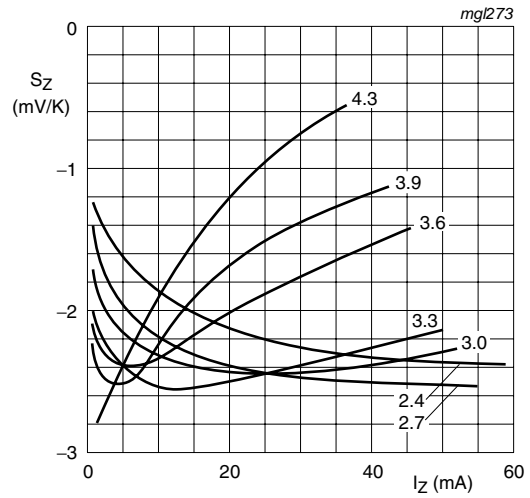
| PZU xxx | Sel | Working voltage V_Z (V); $I_Z = 5\text{ mA}$ | | Maximum differential resistance r_{dif} (Ω) | | Reverse current I_R (nA) | | Temperature coefficient S_Z (mV/K); $I_Z = 5\text{ mA}$ | Diode capacitance C_d (pF) ^[1] | Non-repetitive peak reverse current I_{ZSM} (A) ^[2] |
|------------|-----|---|-------|--|---------------------|----------------------------------|-----------|--|---|--|
| | | Min | Max | $I_Z = 0.5\text{ mA}$ | $I_Z = 5\text{ mA}$ | Max | V_R (V) | Typ | Max | Max |
| 15 | B | 13.84 | 15.52 | 80 | 15 | 50 | 11 | 11.4 | 99 | 2 |
| | B1 | 13.84 | 14.46 | | | | | | | |
| | B2 | 14.34 | 14.98 | | | | | | | |
| | B3 | 14.85 | 15.52 | | | | | | | |
| 16 | B | 15.37 | 17.09 | 80 | 20 | 50 | 12 | 12.4 | 97 | 1.5 |
| | B1 | 15.37 | 16.01 | | | | | | | |
| | B2 | 15.85 | 16.51 | | | | | | | |
| | B3 | 16.35 | 17.09 | | | | | | | |
| 18 | B | 16.94 | 19.03 | 80 | 20 | 50 | 13 | 14.4 | 93 | 1.5 |
| | B1 | 16.94 | 17.70 | | | | | | | |
| | B2 | 17.56 | 18.35 | | | | | | | |
| | B3 | 18.21 | 19.03 | | | | | | | |
| 20 | B | 18.86 | 21.08 | 100 | 20 | 50 | 15 | 16.4 | 88 | 1.5 |
| | B1 | 18.86 | 19.70 | | | | | | | |
| | B2 | 19.52 | 20.39 | | | | | | | |
| | B3 | 20.21 | 21.08 | | | | | | | |
| 22 | B | 20.88 | 23.17 | 100 | 25 | 50 | 17 | 18.4 | 84 | 1.3 |
| | B1 | 20.88 | 21.77 | | | | | | | |
| | B2 | 21.54 | 22.47 | | | | | | | |
| | B3 | 22.23 | 23.17 | | | | | | | |
| 24 | B | 22.93 | 25.57 | 120 | 30 | 50 | 19 | 20.4 | 80 | 1.3 |
| | B1 | 22.93 | 23.96 | | | | | | | |
| | B2 | 23.72 | 24.78 | | | | | | | |
| | B3 | 24.54 | 25.57 | | | | | | | |
| 27 | B | 25.1 | 28.9 | 150 | 40 | 50 | 21 | 23.4 | 73 | 1 |
| 30 | B | 28 | 32 | 200 | 40 | 50 | 23 | 26.6 | 66 | 1 |
| 33 | B | 31 | 35 | 250 | 40 | 50 | 25 | 29.7 | 60 | 0.9 |
| 36 | B | 34 | 38 | 300 | 60 | 50 | 27 | 33.0 | 59 | 0.8 |

[1] $f = 1\text{ MHz}$; $V_R = 0\text{ V}$ [2] $t_p = 100\text{ }\mu\text{s}$; square wave; $T_j = 25\text{ °C}$ prior to surge



$T_j = 25\text{ }^\circ\text{C}$

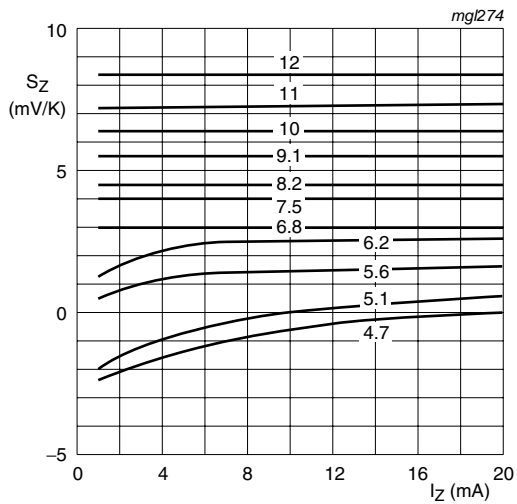
Fig 1. Forward current as a function of forward voltage; typical values



PZU2.4B to PZU4.3B

$T_j = 25\text{ }^\circ\text{C}$ to $150\text{ }^\circ\text{C}$

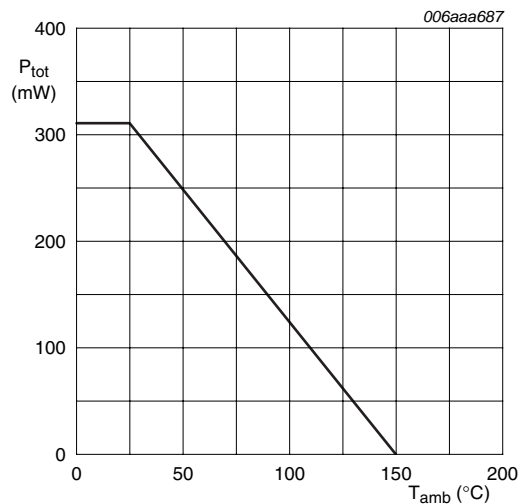
Fig 2. Temperature coefficient as a function of working current; typical values



PZU4.7B to PZU12B

$T_j = 25\text{ }^\circ\text{C}$ to $150\text{ }^\circ\text{C}$

Fig 3. Temperature coefficient as a function of working current; typical values



FR4 PCB, standard footprint

Fig 4. Power derating curve

8. Package outline

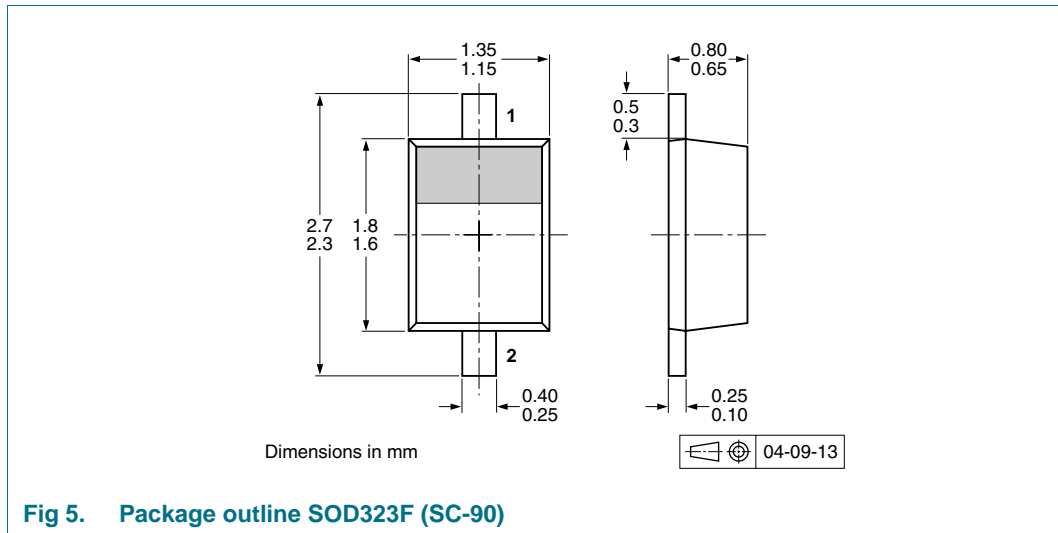


Fig 5. Package outline SOD323F (SC-90)

9. Packing information

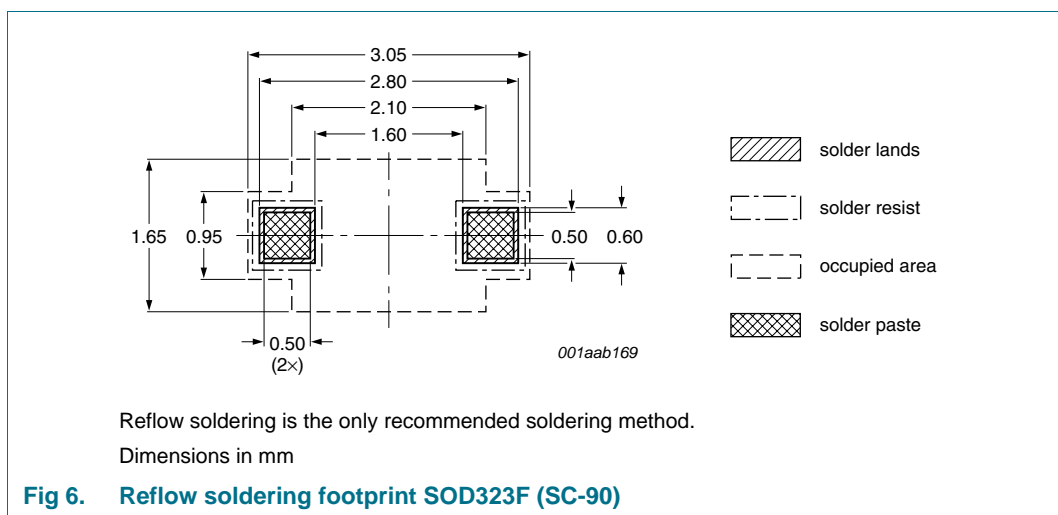
Table 10. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

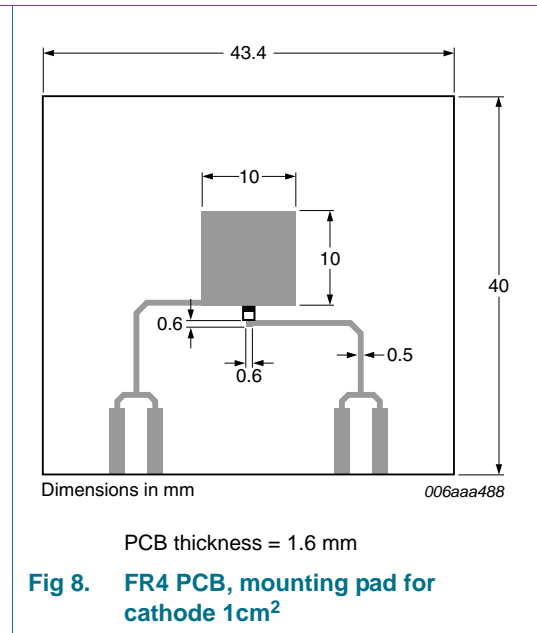
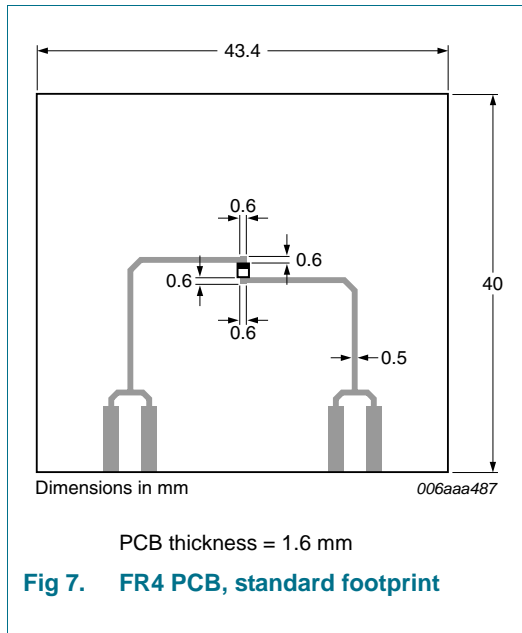
| Type number | Package | Description | Packing quantity | |
|-------------------|---------|--------------------------------|------------------|-------|
| | | | 3000 | 10000 |
| PZU2.4B to PZU36B | SOD323F | 4 mm pitch, 8 mm tape and reel | -115 | -135 |

[1] For further information and the availability of packing methods, see [Section 14](#).

10. Soldering



11. Mounting



12. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|----------------|---|--------------------|---------------|-------------|
| PZUXB_SER_2 | 20091115 | Product data sheet | - | PZUXB_SER_1 |
| Modifications: | <ul style="list-style-type: none">This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content. | | | |
| PZUXB_SER_1 | 20060307 | Product data sheet | - | - |

13. Legal information

13.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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15. Contents

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